

1A, 100V - 200V Ultra Fast Surface Mount Rectifier

FEATURES

- AEC-Q101 qualified
- Planar technology
- Ideal for automated placement
- Low reverse leakage
- Moisture sensitivity level: level 1, per J-STD-020
- RoHS Compliant
- Halogen-free according to IEC 61249-2-21

ΔP	DΙ	ICA	TI	O	NS
_				•	

- DC to DC converter
- Automotive application
- Car lighting
- Snubber
- Freewheeling application

MECHANICAL DATA

- Case: Micro SMA
- Molding compound meets UL 94V-0 flammability rating
- Terminal: Matte tin plated leads, solderable per J-STD-002
- Meet JESD 201 class 2 whisker test
- Polarity: Indicated by cathode band
- Weight: 0.006g (approximately)

KEY PARAMETERS				
PARAMETER VALUE UNI				
I _F	1	Α		
V_{RRM}	100 - 200	V		
I _{FSM}	28	Α		
T _{J MAX}	175	°C		
Package	Micro SMA			









Micro SMA



ABSOLUTE MAXIMUM RATINGS (T _A = 25°C unless otherwise noted)						
PARAMETER	SYMBOL	PU1BMH	PU1DMH	UNIT		
Marking code on the device			P1	P2		
Repetitive peak reverse voltage		V_{RRM}	100	200	V	
Reverse voltage, total rms value		V _{R(RMS)}	70	140	V	
Forward current		I _F	1		Α	
Surge peak forward current single half	t = 8.3ms		28		Α	
sine-wave superimposed on rated load	t = 1.0ms	- I _{FSM} -	52		Α	
Junction temperature		TJ	-55 to +175		°C	
Storage temperature		T _{STG}	-55 to +175		°C	

1

Taiwan Semiconductor

THERMAL PERFORMANCE					
PARAMETER	SYMBOL	TYP	UNIT		
Junction-to-lead thermal resistance	$R_{\Theta JL}$	28	°C/W		
Junction-to-ambient thermal resistance	$R_{\Theta JA}$	60	°C/W		
Junction-to-case thermal resistance	R _{eJC}	34	°C/W		

Thermal Performance Note: Units mounted on PCB (5mm x 5mm Cu pad test board)

ELECTRICAL SPECIFICATIONS (T _A = 25°C unless otherwise noted)					
PARAMETER	CONDITIONS	SYMBOL	TYP	MAX	UNIT
	$I_F = 0.5A, T_J = 25^{\circ}C$		0.84	-	V
Forward voltage ⁽¹⁾	$I_F = 1.0A, T_J = 25^{\circ}C$	V	0.90	1.05	V
Forward voltage	I _F = 0.5A, T _J = 125°C	V _F	0.70	-	V
	I _F = 1.0A, T _J = 125°C		0.76	0.90	V
Reverse current @ rated V _B ⁽²⁾	$T_J = 25$ °C		-	1	μΑ
Reverse current @ rated V _R	T _J = 125°C	- I _R	-	15	μΑ
Payaraa raaayary tima	$I_F = 0.5A, I_R = 1.0A, I_{rr} = 0.25A$	+	-	25	- ns
Reverse recovery time	$I_F=1.0A,di/dt=50A/\mu s,V_R=30V$	- t _{rr}	36	-	
Reverse recovery current		I _{RM}	3.4	-	Α
Reverse recovery charge	$I_F = 1.0A$, di/dt = 200A/ μ s, $V_R = 100V$	Q _{rr}	40	-	nC
Reverse recovery time		t _{rr}	24	-	ns
Junction capacitance	1MHz, V _R = 4.0V	CJ	18	-	pF

Notes:

- (1) Pulse test with PW = 0.3ms
- (2) Pulse test with PW = 30ms

ORDERING INFORMATION				
ORDERING CODE ⁽¹⁾	PACKAGE	PACKING		
PU1xMH	Micro SMA	12,000 / Tape & Reel		

Notes:

1. "x" defines voltage from 100V(PU1BMH) to 200V(PU1DMH)



CHARACTERISTICS CURVES

 $(T_A = 25^{\circ}C \text{ unless otherwise noted})$

Fig.1 Forward Current Derating Curve

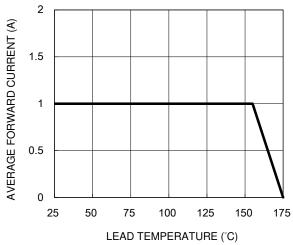


Fig.3 Typical Reverse Characteristics



Fig.2 Typical Junction Capacitance

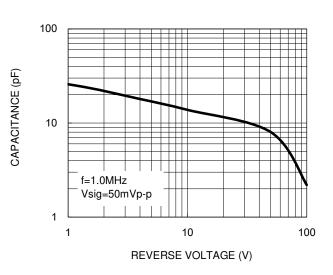
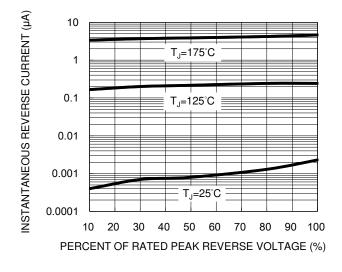


Fig.4 Typical Forward Characteristics



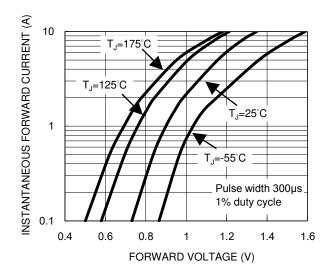
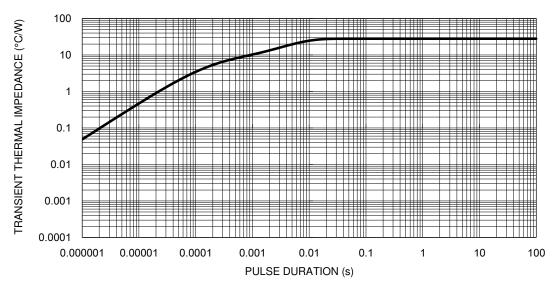


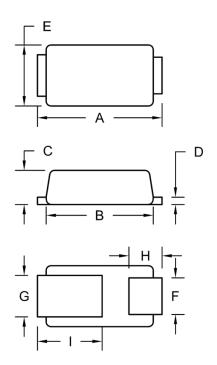
Fig.5 Typical Transient Thermal Impedance





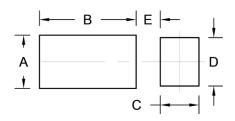
PACKAGE OUTLINE DIMENSIONS

Micro SMA



DIM.	Unit (mm)		Unit (inch)	
Dilvi.	Min.	Max.	Min.	Max.
Α	2.30	2.70	0.091	0.106
В	2.10	2.30	0.083	0.091
С	0.63	0.73	0.025	0.029
D	0.10	0.20	0.004	0.008
E	1.15	1.35	0.045	0.053
F	0.65	0.85	0.026	0.034
G	0.75	0.95	0.030	0.037
Н	0.55	0.75	0.022	0.030
I	1.10	1.50	0.043	0.059

SUGGESTED PAD LAYOUT



Symbol	Unit (mm)	Unit (inch)
Α	1.10	0.043
В	2.00	0.079
С	0.80	0.031
D	1.00	0.039
E	0.50	0.020

MARKING DIAGRAM



= Marking Code P/N YW = Date Code



Taiwan Semiconductor

Notice

Specifications of the products displayed herein are subject to change without notice. TSC or anyone on its behalf, assumes no responsibility or liability for any errors or inaccuracies.

Purchasers are solely responsible for the choice, selection, and use of TSC products and TSC assumes no liability for application assistance or the design of Purchasers' products.

Information contained herein is intended to provide a product description only. No license, express or implied, to any intellectual property rights is granted by this document. Except as provided in TSC's terms and conditions of sale for such products, TSC assumes no liability whatsoever, and disclaims any express or implied warranty, relating to sale and/or use of TSC products including liability or warranties relating to fitness for a particular purpose, merchantability, or infringement of any patent, copyright, or other intellectual property right.

The products shown herein are not designed for use in medical, life-saving, or life-sustaining applications. Customers using or selling these products for use in such applications do so at their own risk and agree to fully indemnify TSC for any damages resulting from such improper use or sale.